

TOSHIBA LED Lamp InGaA/P Red/Green Light Emission

TLRMHGH48T(F)

○ Bi-Color High Luminosity Indicator

- High luminous intensity
- 5-mm package
- InGaA/P Red/Green LED with a common cathode
- Plastic-molded
- Transparent lens

Absolute Maximum Ratings (Ta = 25°C)

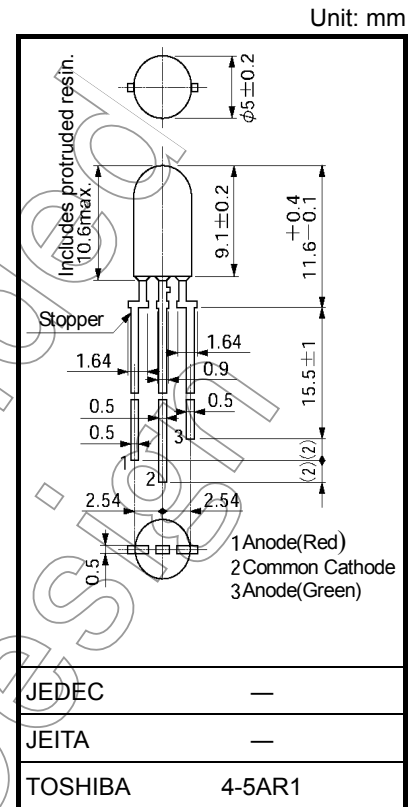
Characteristics	Symbol	Rating	Unit
Forward Current	I _F	50 (Note 1)	mA
Reverse Voltage	V _R	4	V
Power Dissipation	P _D	120	(mW)
Power Dissipation	T _{opr}	-40 to 100	°C
Operating Temperature	T _{stg}	-40 to 120	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

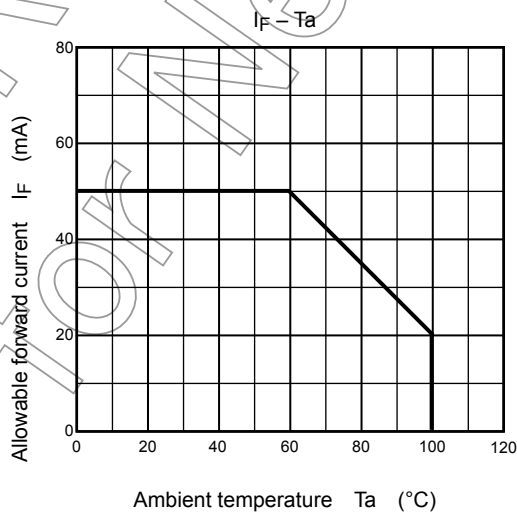
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Per-device I_F-Ta rating.

When both the red and green LEDs are lit up, the sum of their forward currents should be within the rated value.



Weight: 0.37 g (typ.)



Electrical and Optical Characteristics (Ta = 25°C)

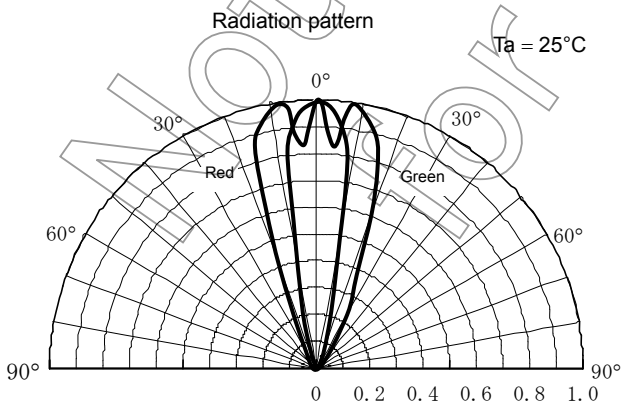
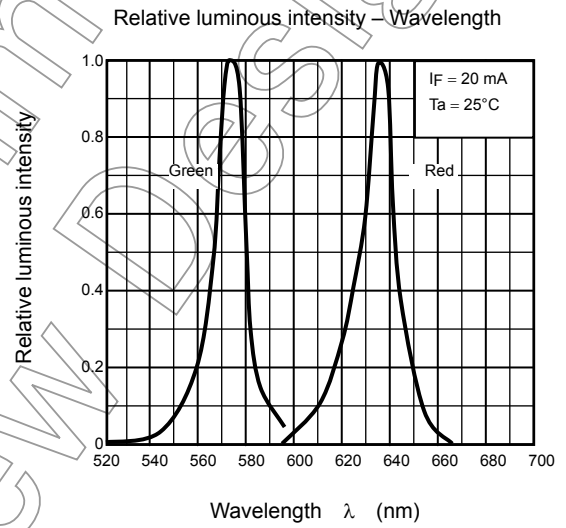
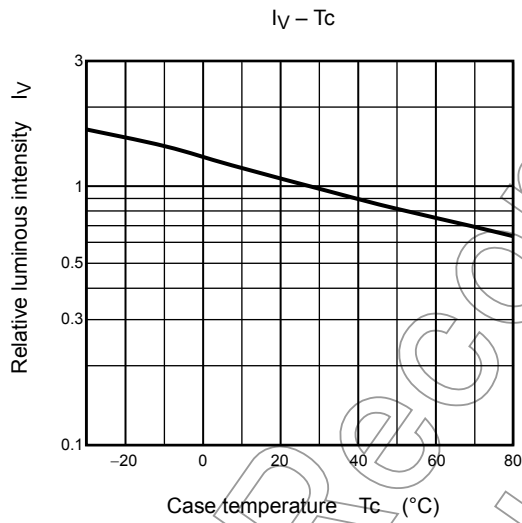
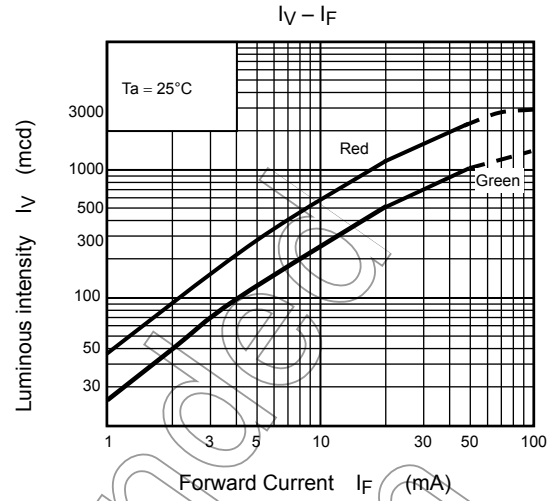
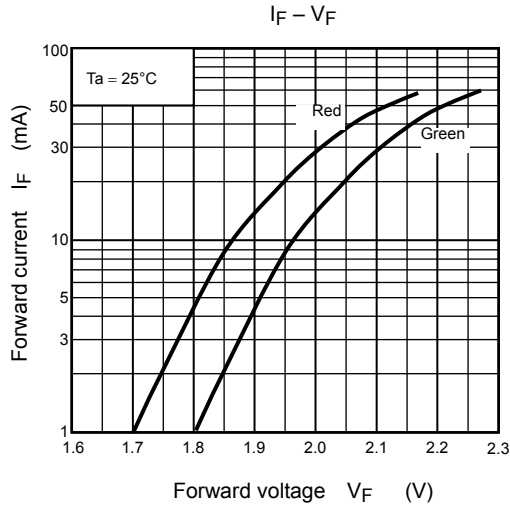
Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Forward Voltage	Red	V _F	I _F = 20 mA	—	1.95	2.4	V
	Green			—	2.05	2.4	
Reverse Current	Red	I _R	V _R = 4 V	—	—	50	μA
	Green			—	—	50	
Luminous Intensity	Red	I _v	I _F = 20 mA	476	1100	—	mcd
	Green			272	500	—	
Spectral Line Half Width	Red	Δλ	I _F = 20 mA	—	13	—	nm
	Green			—	13	—	
Dominant Wavelength	Red	λ _d	I _F = 20 mA	—	626	—	nm
	Green			—	571	—	

Precautions

Please be careful of the followings

- Soldering temperature : 260C°max Soldering time :3 s max (Soldering portion of lead : below the lead stopper of the device)
- If the lead is formed, the lead should be formed up to below the lead stopper of the device without Formed stress to the resin. Soldering should be performed after lead forming.
- The visible LED lamp also emits some IR light.
If a photodetector is located near the LED lamp, please ensure that it will not be affected by the IR light.

Not Recommended for New Design



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